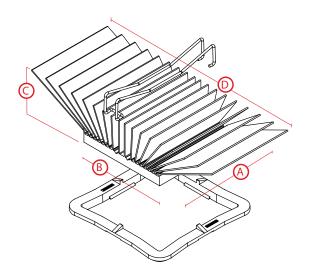


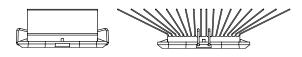
# Ultra High Performance BGA Cooling Solutions w/ maxiGRIP™ Attachment

## ATS PART # ATS-50230P-C2-R0

### **Features & Benefits**

- » maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- » maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB
- » Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards
- » Comes preassembled with high performance, phase changing, thermal interface material
- » Designed for standard height components from 3 to 4.5mm





#### \*Image above is for illustration purposes only.

# **Thermal Performance**

AIR VELOCITY		THERMAL RESISTANCE		
M/S	°C/W (UNDUCTED FLOW)	°C/W (DUCTED FLOW)		
1.0	5.1	4.1		
1.5	4.2			
2.0	3.6			
2.5	3.3			
3.0	3			
3.5	2.8			
4.0	2.6			
	M/S 1.0 1.5 2.0 2.5 3.0 3.5	M/S °C/W (UNDUCTED FLOW)  1.0 5.1  1.5 4.2  2.0 3.6  2.5 3.3  3.0 3  3.5 2.8		

# **Product Details**

DIMENSION A	DIMENSION B	DIMENSION C	DIMENSION D	INTERFACE MATERIAL	FINISH
23 mm	23 mm	17.5 mm	41.5 mm	SAINT-GOBAIN C1100F	BLUE-ANODIZED

#### NOTES:

- Dimension C = heat sink height from bottom of the base to the top of the fin field.
- ATS-50230P-C1-R0 is a substitute item available utilizing an equivalent phase change material (Chomerics T766).
- Thermal performance data are provided for reference only. Actual performance may vary by application.
- ATS reserves the right to update or change its products without notice to improve the design or performance.
- 5) Optional maxiGRIP™ Installation/Removal Tool Set P/N: MGT230
- 6) Contact ATS to learn about custom options available.



For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).